描述 / Descriptions

SOT-23 塑封封装 N 沟道 MOS 场效应管。
N- CHANNEL MOSFET in a SOT-23 Plastic Package.

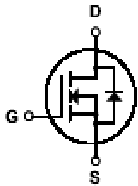
特征 / Features

芯片采用超高密度元胞设计技术，$R_{DS(ON)}$导通电阻小，SOT-23 封装。
Super high dense cell design for low $R_{DS(ON)}$,SOT-23 package.

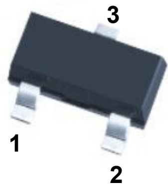
用途 / Applications

电池管理，高速开关，低功率 DC-DC 转换。
Battery management,High speed switch,low power DC to DC converter.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1：G　　PIN 2：S　　PIN 3：D

印章代码 / Marking

Marking	A2H

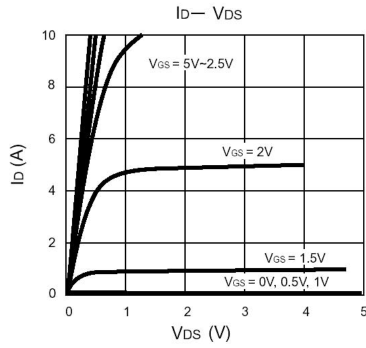
极限参数 / Absolute Maximum Ratings(Ta=25℃)

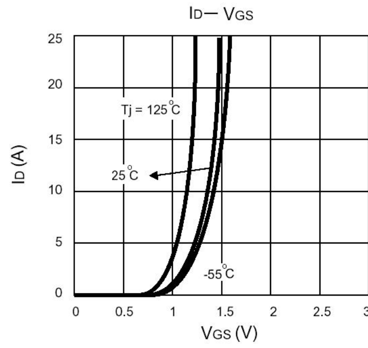
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	±10	V
Drain Current – Continuous	I_D	3.0	A
Pulsed Drain Current	I_{DM}	10	A
Continuous Source Current	I_S	0.95	A
Power Dissipation	P_D	0.9	W
Storage Temperature Range	T_{stg}	-55～150	℃

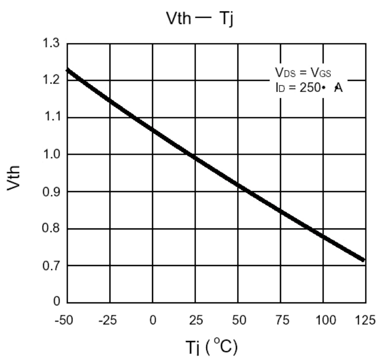
电性能参数 / Electrical Characteristics(Ta=25℃)

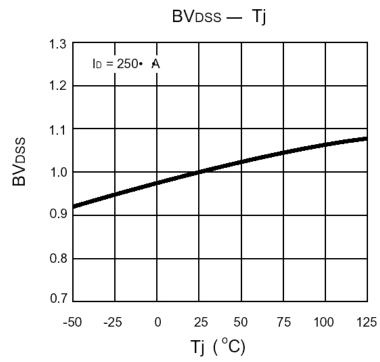
参数 Parameter	符号 Symbol	测试条件 Test Conditions		最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain–Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0	I_D=10μA	20	21		V
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS}=0	V_{DS}=20V			1.0	μA
Gate–Body Leakage.	I_{GSS}	V_{GS}=±10V	V_{DS}=0V			±100	nA
Static Drain–Source On–Resistance	$R_{DS(on)1}$	V_{GS}=4.5V	I_D=3.6A		46	55	mΩ
	$R_{DS(on)2}$	V_{GS}=2.5V	I_D=3.1A		59	75	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V	I_D=3.6A		6		S
Drain–Source Diode Forward Voltage	V_{SD}	V_{GS}=0V	I_D=1.25A			1.2	V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}	I_D=50μA	0.50		1.0	V
Turn–On Delay Time	$t_{d(on)}$	V_{DD}=10V V_{GEN}=4.5V R_{GEN}=6Ω	I_D=3.6A R_L=2.8Ω		7		ns
Turn–On Rise Time	t_r				55		
Turn–Off Delay Time	$t_{d(off)}$				15		
Turn–Off Fall Time	t_f				10		

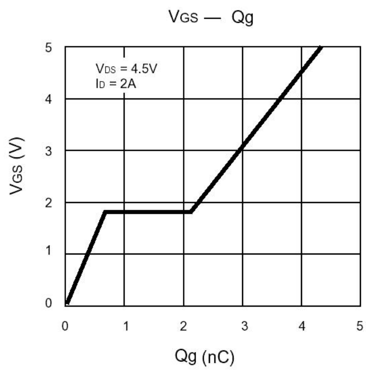
电参数曲线图 / Electrical Characteristic Curve

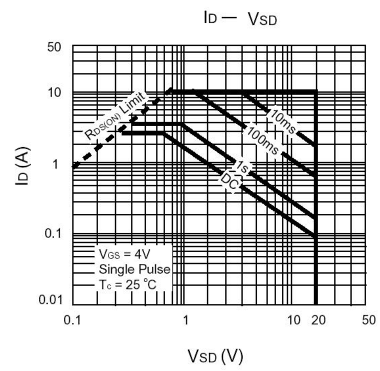


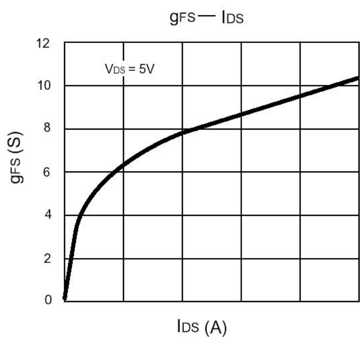


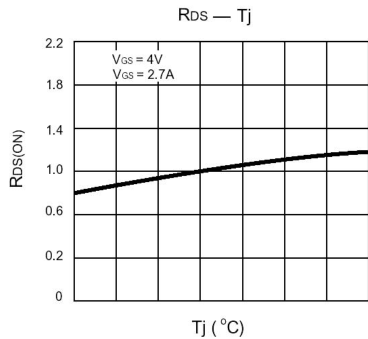






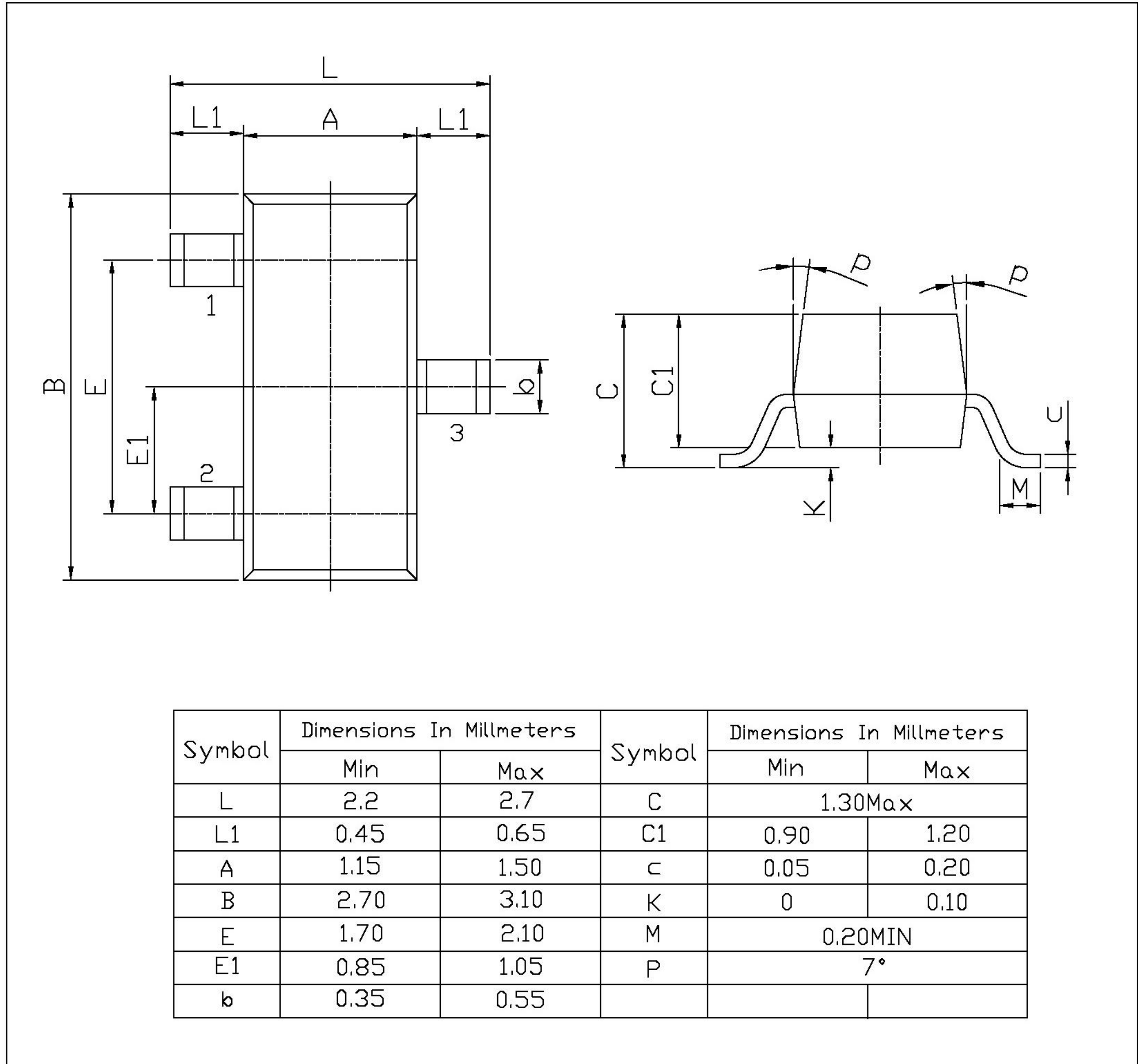






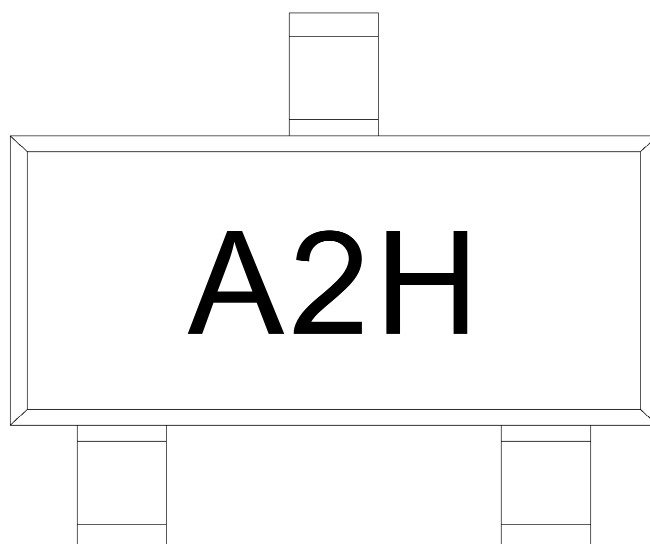
外形尺寸图 / Package Dimensions

SOT-23 单位：mm



Symbol	Dimensions In Millmeters		Symbol	Dimensions In Millmeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10
E	1.70	2.10	M	0.20MIN	
E1	0.85	1.05	P	7°	
b	0.35	0.55			

印章说明 / Marking Instructions



说明：

A2: 为型号代码

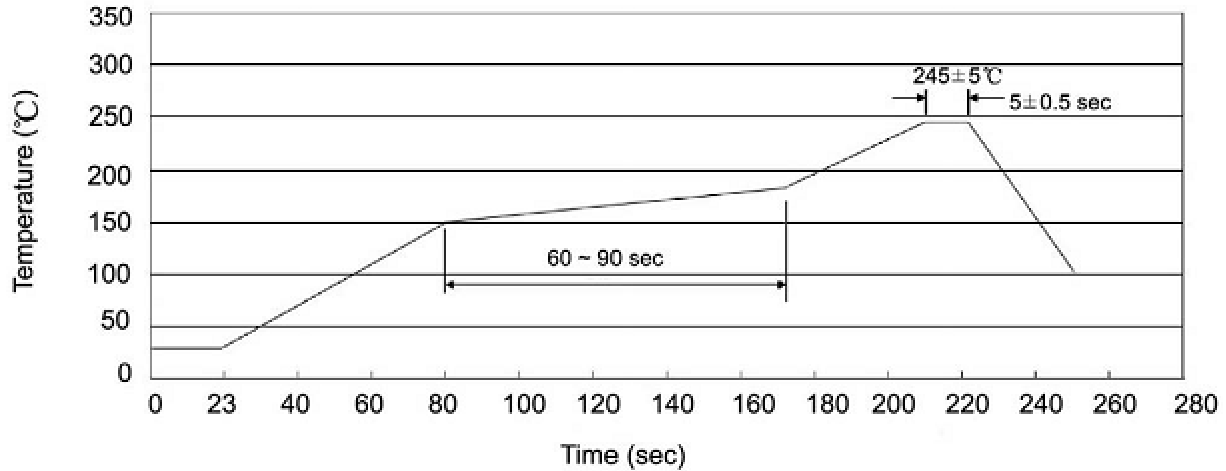
H: 为公司代码

Note:

A2： Product Type Code

H: Company Code.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

1、预热温度 25～150℃，时间 60～90sec;

2、峰值温度 245±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:25~150℃, Time:60~90sec.

2.Peak Temp.:245±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃　　时间：10±1 sec.

Temp.:260±5℃　　Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

使用说明 / Notices